

Stand allocation begins: 1 February 2012

Main Exhibitor (Correspondence/billing address)

Company

 Contact person Hall / Stand no.
 Ms
 Mr
 Street / P. O. Box

 Country ID / Postal Code Town

We hereby authorize the company named below to exhibit at our stand as a co-exhibitor.

The company has all technical and commercial documents necessary for the information of visitors concerning the exhibits on display. The exhibits correspond to the index of products and services (cf. A4 of the General Terms of Participation A).

Please note para. B 3 "Co-exhibitors and additionally represented companies"

and B 4 b) "Obligatory communication fee."

Registration fee per co-exhibitor admitted
Obligatory communication fee

EUR 200
EUR 280

Co-exhibitor additionally represented company

Company

 Street

 Postal Code Town

 Country

VAT-ID No. (required by VAT legislation)

Number and place of company registration

 Email (personalized)

 Homepage

Manufacturer Dealer Importer Distributor with exclusive selling rights for Germany (multiple responses possible)
 Service company Member of the following trade association/s: _____

Applicants who are based in Germany or in the European Union: In the case of the given applicant, his/her company carries out business-related activities autonomously for the purpose of earning income on a sustainable basis (Art. 9 MwStSystRL). The applicant herewith declares that he/she is sourcing the services provided by Messe München GmbH for his/her company.

Applicants who are based in a country outside the European Union: In the case of the given applicant, his/her company carries out business-related activities autonomously for the purpose of earning income on a sustainable basis (Art. 9 MwStSystRL). The applicant herewith declares that he/she is sourcing the services provided by Messe München GmbH for his/her company.

Neither of the above declarations is applicable. In such cases, Messe München GmbH will charge for its services plus statutory German sales tax even if the given applicant is based abroad.

Contact person for trade fair organization Title/First name/Last name

Ms
 Mr
 Phone number and extension Fax

Job function

Email (personalized)

Please tick in the product index under which product category/focal area of activity your exhibits should be listed.

Please change the correspondence/billing address to the name and address of the co-exhibitor. Services ordered from Messe München by the co-exhibitor shall also be charged directly to the co-exhibitor.

Please take note of the Participation Terms A and B and the Technical Guidelines.

I have read the Participation Terms A and B and the Technical Guidelines submitted with the application forms of the main exhibitor and recognize them as legally binding in all parts.

Please note:

The details given here serve to determine the optimal location for your stand within the LOPE-C sectors. If you plan on having products/services from more than one main product group on exhibit, please indicate the preferred category in which your exhibition stand should be placed.

Please send to:

Messe München GmbH
Messegelände
81823 München, Germany

Exhibition management LOPE-C

Main exhibitor

Company

Hall/Stand no.

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Co-exhibitor/additionally represented company

Company

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Product Index/Exhibition Sector LOPE-C 2012 – Co-exhibitor

Please tick only one product group which is the focus of your business activities.

1. Materials

1.1 Substrates

- 1.1.1 Plastic films
- 1.1.2 Metal foils
- 1.1.3 Paper
- 1.1.4 Glass
- 1.1.5 Textile
- 1.1.6 Other substrates

1.2 Conductors

- 1.2.1 Organic conductors
- 1.2.2 Inorganic conductors
- 1.2.3 Nano materials
- 1.2.4 Carbon nanotubes
- 1.2.5 Hybrides

1.3 Semiconductors

- 1.3.1 Semiconductors
- 1.3.2 Polymer
- 1.3.3 Small molecule
- 1.3.4 Inorganic semiconductors
- 1.3.5 Nano materials
- 1.3.6 Hybrides

1.4 Dielectrics

- 1.4.1 Organic dielectrics
- 1.4.2 Inorganic dielectrics
- 1.4.3 Nano materials
- 1.4.4 Carbon nanotubes
- 1.4.5 Hybrides

1.5 Encapsulation materials and resins

- 1.5.1 Thin film encapsulation
- 1.5.2 Polymer film encapsulation
- 1.5.3 Metal encapsulation
- 1.5.4 Glass encapsulation
- 1.5.5 Resins

1.6 Components for hybrid systems (Polytronics)

- 1.7 Other materials

2. Manufacturing Processes

2.1 Mass patterning techniques

- 2.1.1 Gravure printing
- 2.1.2 Offset printing
- 2.1.3 Flexographic printing
- 2.1.4 Screen printing

2.2 Digital printing

- 2.2.1 Inkjet
- 2.2.2 Other digital printing

2.3 Other printing processes

- 2.3.1 μ CP
- 2.3.2 Nano imprint
- 2.3.3 Other printing processes

2.4 Vacuum processes

- 2.4.1 Evaporation
- 2.4.2 Sputtering
- 2.4.3 Organic vapor phase deposition (OVPD)

2.5 Photolithography

2.6 Laser

- 2.6.1 Laser Ablation
- 2.6.2 Laser Transfer

2.7 Solution coating

- 2.7.1 Spin coating
- 2.7.2 Dip coating
- 2.7.3 Blade coating
- 2.7.4 Other solution coating

2.8 Encapsulation

- 2.8.1 Thin film encapsulation
- 2.8.2 Polymer film encapsulation
- 2.8.3 Metal encapsulation
- 2.8.4 Glass encapsulation
- 2.8.5 Other encapsulation processes

2.9 Clean room

2.10 Roll-to-roll process

- 2.11 Other manufacturing processes

Main exhibitor

Company

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Company

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Please tick only one product group which is the focus of your business activities.

3. Assembly and packaging technology, system integration

- 3.1 Electrical contacting**
- 3.1.1 Flip Chip
- 3.1.2 Other electrical contacting
- 3.2 Lamination**
- 3.3 System integration**
- 3.4 Hybrid systems (Polytronics)**

4. Inspection and test systems

- 4.1 Electrical characterization**
- 4.2 Physical/Optical characterization**
- 4.3 Chemical characterization**
- 4.4 Simulation/Circuit optimization**
- 4.5 Lifetime testing**
- 4.6 Quality/Process control**
- 4.7 Environmental testing**
- 4.8 Other inspection and test systems**

5. Devices

- 5.1 Transistors**
- 5.2 Diodes**
- 5.3 Passives**
- 5.3.1 Capacitors
- 5.3.2 Resistors
- 5.3.3 Other passives
- 5.4 Integrated circuits**
- 5.5 Displays**
- 5.5.1 OLED
- 5.5.2 Electrophoretic
- 5.5.3 Electrochromic
- 5.5.4 Electroluminescent
- 5.5.5 LCD
- 5.5.6 Electrowetting
- 5.5.7 Other displays
- 5.6 Photovoltaic cells**
- 5.6.1 Organic photovoltaic cells
- 5.6.2 Hybrid photovoltaic cells
- 5.6.3 Inorganic photovoltaic cells

5.7 Sensors

- 5.7.1 Photodiode
- 5.7.2 Pressure
- 5.7.3 Temperature
- 5.7.4 Gas
- 5.7.5 Other sensors
- 5.8 Memory elements**
- 5.9 Antennas**
- 5.10 Batteries**
- 5.11 Other devices**

6. Applications

- 6.1 RFID**
- 6.2 TFT backplanes**
- 6.3 Displays**
- 6.4 Sensors**
- 6.5 Smart objects**
- 6.6 Solar cells**
- 6.7 Smart textiles**
- 6.8 Speakers**
- 6.9 Lighting**
- 6.10 Other applications**

7. Services

- 7.1 Consulting**
- 7.2 R&D funding management**
- 7.3 R&D**
- 7.4 Prototyping**
- 7.5 Manufacturing**
- 7.6 Venture and equity capitalization**
- 7.7 Professional and trade associations**
- 7.8 Technical books, technical journals, periodicals, publications**